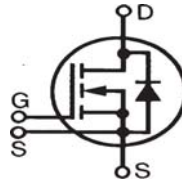


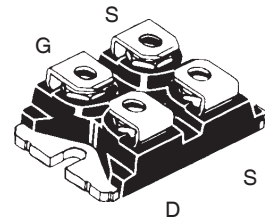
**Linear L2™ Power  
MOSFET**
**IXTN60N50L2**

 N-Channel Enhancement Mode  
Extended FBSOA


$$V_{DSS} = 500V$$

$$I_{D25} = 53A$$

$$R_{DS(on)} \leq 100m\Omega$$

 miniBLOC, SOT-227  
 E153432

 G = Gate      D = Drain  
 S = Source

Either source terminal S can be used as the source terminal or the Kelvin source (gate return) terminal.

Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ C$ to $150^\circ C$	500	V
$V_{DGR}$	$T_J = 25^\circ C$ to $150^\circ C$ , $R_{GS} = 1M\Omega$	500	V
$V_{GSS}$	Continuous	$\pm 30$	V
$V_{GSM}$	Transient	$\pm 40$	V
$I_{D25}$	$T_C = 25^\circ C$	53	A
$I_{DM}$	$T_C = 25^\circ C$ , pulse width limited by $T_{JM}$	150	A
$I_A$	$T_C = 25^\circ C$	60	A
$E_{AS}$	$T_C = 25^\circ C$	3	J
$P_D$	$T_C = 25^\circ C$	735	W
$T_J$		-55 ... +150	$^\circ C$
$T_{JM}$		150	$^\circ C$
$T_{stg}$		-55 ... +150	$^\circ C$
$T_L$	1.6mm (0.062 in.) from case for 10s	300	$^\circ C$
$T_{SOLD}$	Plastic body for 10s	260	$^\circ C$
$V_{ISOL}$	50/60 Hz, RMS $t = 1$ minute	2500	V~
	$I_{ISOL} \leq 1mA$ $t = 1$ second	3000	V~
$M_d$	Mounting torque	1.5/13	Nm/lb.in.
	Terminal Connection torque	1.3/11.5	Nm/lb.in.
<b>Weight</b>		30	g

**Features**

- Designed for linear operation
- International standard package
- Molding epoxy meets UL94 V-0 flammability classification
- miniBLOC with Aluminium nitride isolation

**Applications**

- Programmable loads
- Current regulators
- DC-DC converters
- Battery chargers
- DC choppers
- Temperature and lighting controls

**Advantages**

- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions ( $T_J = 25^\circ C$ , unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{DSS}$	$V_{GS} = 0V$ , $I_D = 1mA$	500		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	2.5		V
$I_{GSS}$	$V_{GS} = \pm 30V$ , $V_{DS} = 0V$			$\pm 200$ nA
$I_{DSS}$	$V_{DS} = V_{DSS}$ $V_{GS} = 0V$ $T_J = 125^\circ C$			50 $\mu A$ 5 mA
$R_{DS(on)}$	$V_{GS} = 10V$ , $I_D = 30A$ Note 1			100 m $\Omega$

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)	Characteristic Values			
		Min.	Typ.	Max.	
$g_{fs}$	$V_{DS} = 10\text{V}, I_D = 30\text{A}$ , Note 1	18	25	32	S
$C_{iss}$	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V}, f = 1\text{MHz}$		24		nF
$C_{oss}$			1325		pF
$C_{rss}$			172		pF
$t_{d(on)}$	<b>Resistive Switching Times</b> $V_{GS} = 15\text{V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 30\text{A}$ $R_G = 0.5\Omega$ (External)		40		ns
$t_r$			40		ns
$t_{d(off)}$			165		ns
$t_f$			38		ns
$Q_{g(on)}$	$V_{GS} = 10\text{V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 30\text{A}$		610		nC
$Q_{gs}$			130		nC
$Q_{gd}$			365		nC
$R_{thJC}$				0.17	$^\circ\text{C/W}$
$R_{thCS}$		0.05			$^\circ\text{C/W}$

### Safe Operating Area Specification

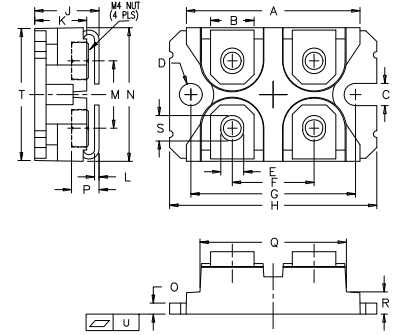
Symbol	Test Conditions	Min.	Typ.	Max.
SOA	$V_{DS} = 400\text{V}, I_D = 0.9\text{A}, T_C = 75^\circ\text{C}, t_p = 3\text{s}$	360		W

### Source-Drain Diode

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)	Characteristic Values			
		Min.	Typ.	Max.	
$I_S$	$V_{GS} = 0\text{V}$			60	A
$I_{SM}$	Repetitive, pulse width limited by $T_{JM}$			240	A
$V_{SD}$	$I_F = I_S, V_{GS} = 0\text{V}$ , Note 1			1.5	V
$t_{rr}$	$I_F = 60\text{A}, -di/dt = 100\text{A}/\mu\text{s}$		980		ns
$I_{RM}$				73	
$Q_{RM}$	$V_R = 100\text{V}, V_{GS} = 0\text{V}$		35.8		$\mu\text{C}$

Note 1: Pulse test,  $t \leq 300\mu\text{s}$ ; duty cycle,  $d \leq 2\%$ .

### SOT-227B (IXTN) Outline



(M4 screws (4x) supplied)

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.240	1.255	31.50	31.88
B	.307	.323	7.80	8.20
C	.161	.169	4.09	4.29
D	.161	.169	4.09	4.29
E	.161	.169	4.09	4.29
F	.587	.595	14.91	15.11
G	1.186	1.193	30.12	30.30
H	1.496	1.505	38.00	38.23
J	.460	.481	11.68	12.22
K	.351	.378	8.92	9.60
L	.030	.033	0.76	0.84
M	.496	.506	12.60	12.85
N	.990	1.001	25.15	25.42
O	.078	.084	1.98	2.13
P	.195	.235	4.95	5.97
Q	1.045	1.059	26.54	26.90
R	.155	.174	3.94	4.42
S	.186	.191	4.72	4.85
T	.968	.987	24.59	25.07
U	-.002	.004	-0.05	0.1

### PRELIMINARY TECHNICAL INFORMATION

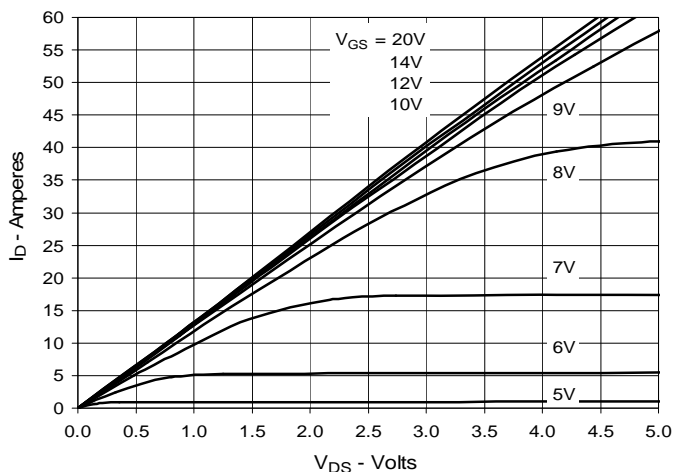
The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

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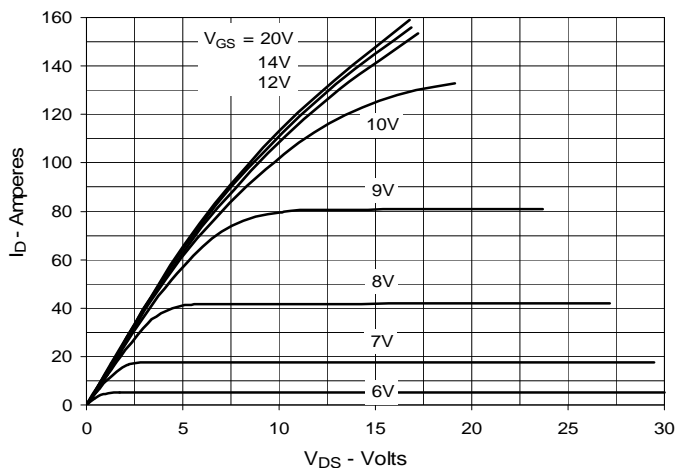
IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
4,850,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

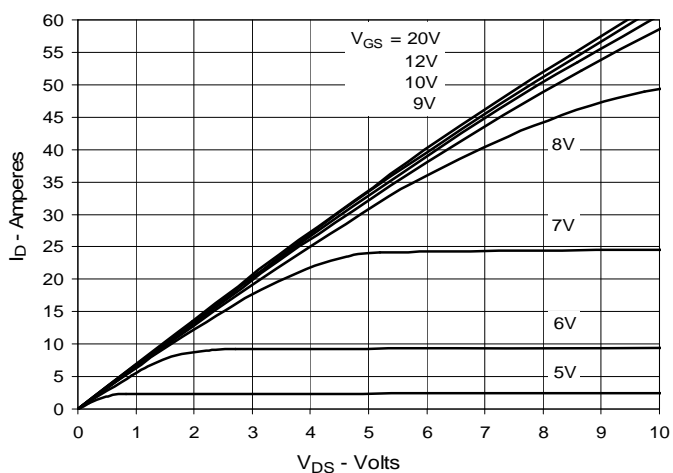
**Fig. 1. Output Characteristics @ 25°C**



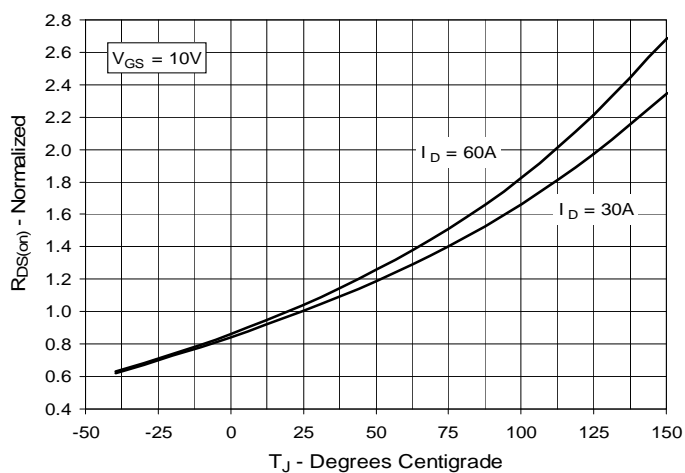
**Fig. 2. Extended Output Characteristics @ 25°C**



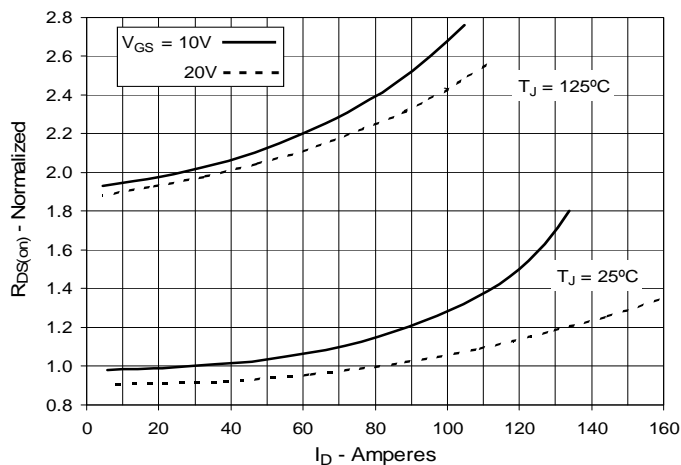
**Fig. 3. Output Characteristics @ 125°C**



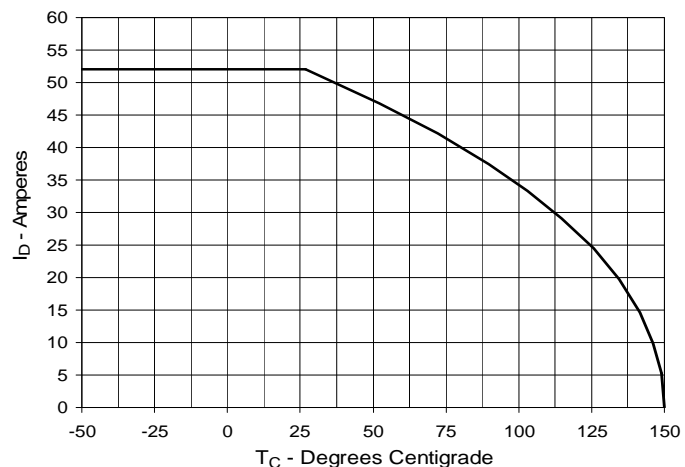
**Fig. 4.  $R_{DS(on)}$  Normalized to  $I_D = 30A$  Value vs. Junction Temperature**

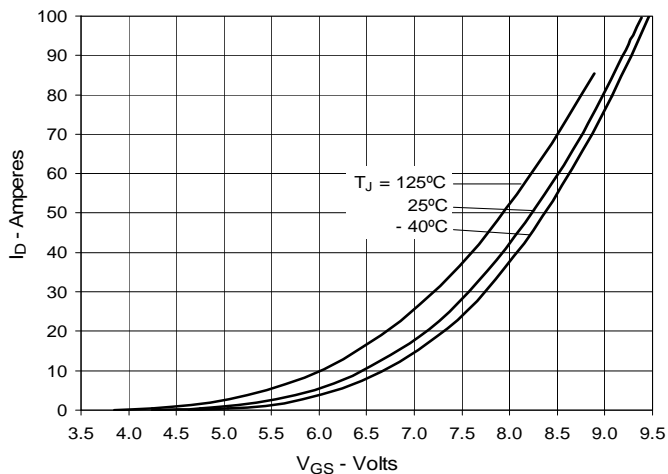
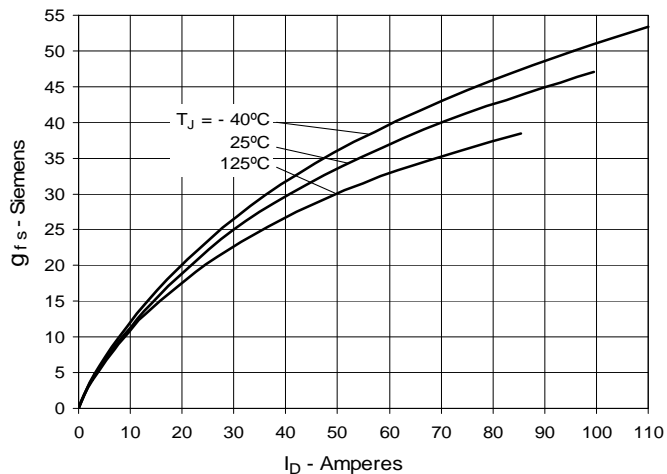
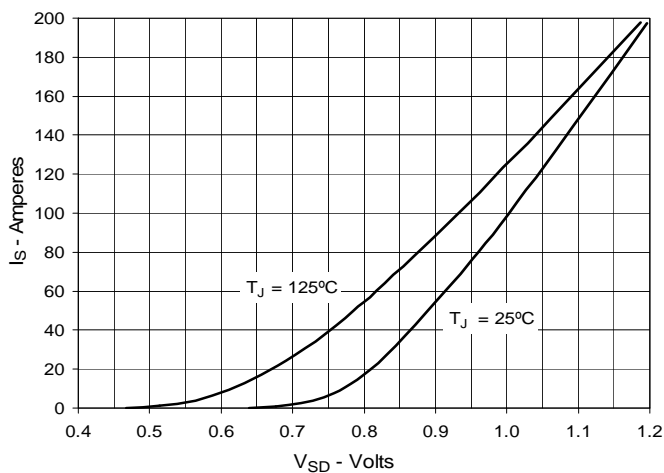
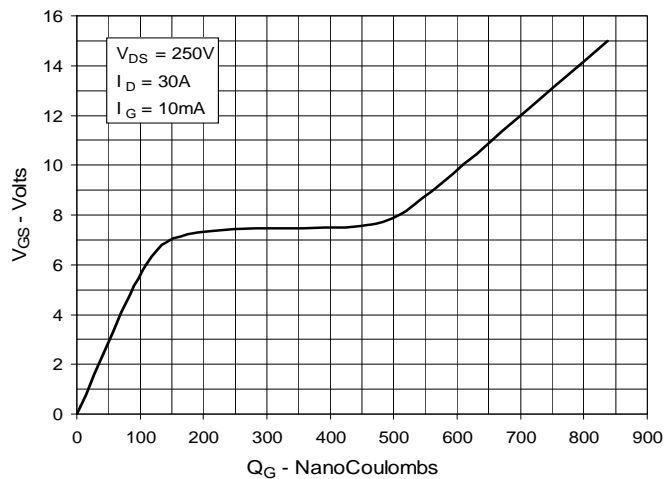
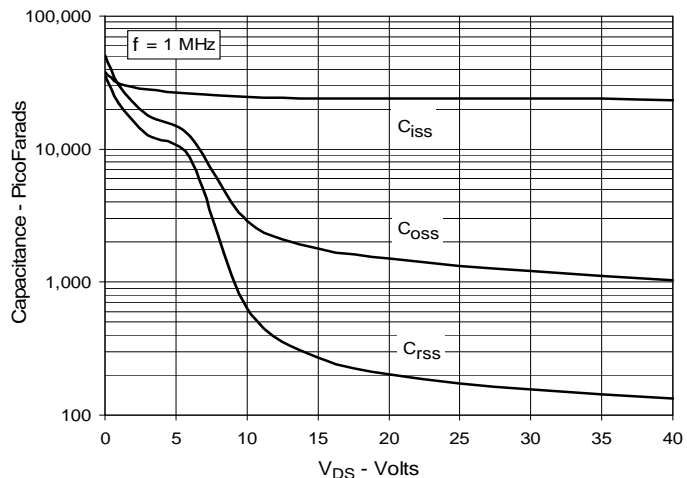
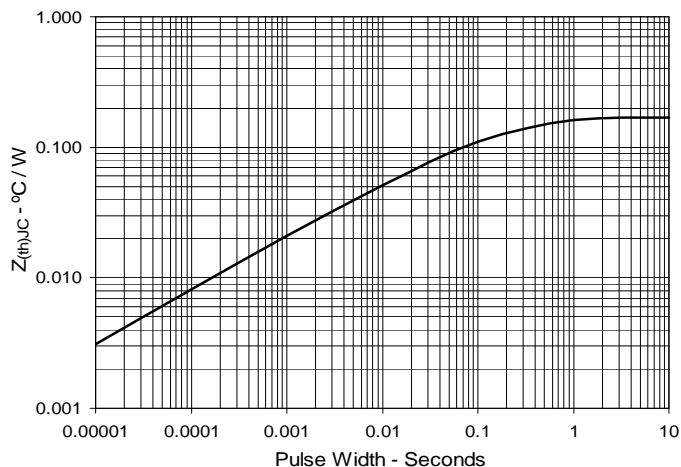


**Fig. 5.  $R_{DS(on)}$  Normalized to  $I_D = 30A$  Value vs. Drain Current**

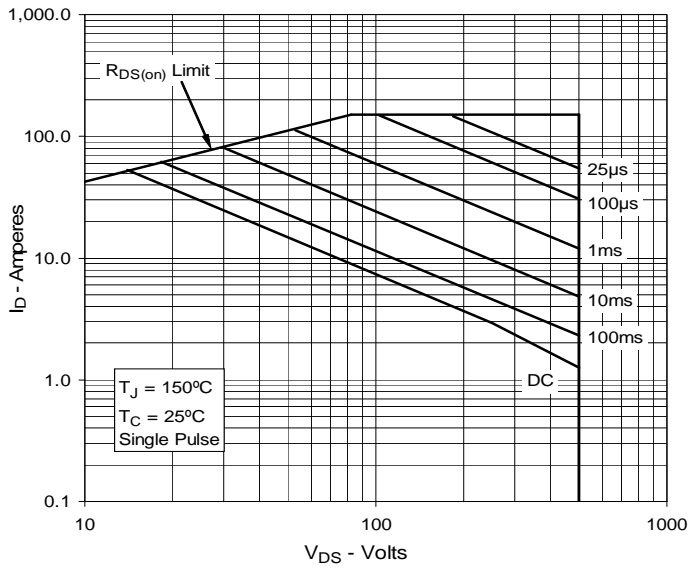


**Fig. 6. Maximum Drain Current vs. Case Temperature**



**Fig. 7. Input Admittance**

**Fig. 8. Transconductance**

**Fig. 9. Forward Voltage Drop of Intrinsic Diode**

**Fig. 10. Gate Charge**

**Fig. 11. Capacitance**

**Fig. 12. Maximum Transient Thermal Impedance**


**Fig. 13. Forward-Bias Safe Operating Area  
@  $T_C = 25^\circ\text{C}$**



**Fig. 14. Forward-Bias Safe Operating Area  
@  $T_C = 75^\circ\text{C}$**

